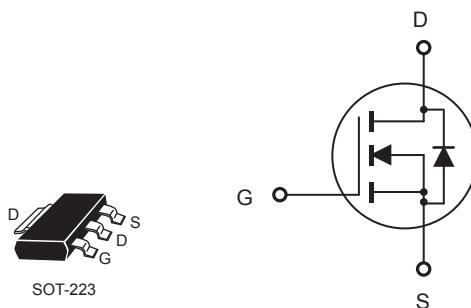


**N-Channel Enhancement Mode Field Effect Transistor****FEATURES**

- 60V, 4A,  $R_{DS(ON)} = 85\text{m}\Omega$  @ $V_{GS} = 10\text{V}$ .  
 $R_{DS(ON)} = 100\text{m}\Omega$  @ $V_{GS} = 5\text{V}$ .
- High dense cell design for extremely low  $R_{DS(ON)}$ .
- Rugged and reliable.
- Lead free product is acquired.
- SOT-223 package.

**ABSOLUTE MAXIMUM RATINGS**  $T_A = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	4	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	16	A
Maximum Power Dissipation	$P_D$	3	W
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{\theta JA}$	42	$^\circ\text{C}/\text{W}$



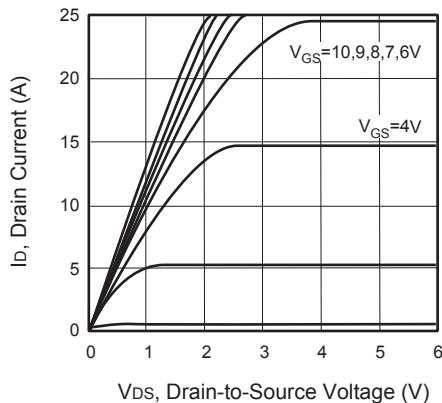
# CET3055L

## Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

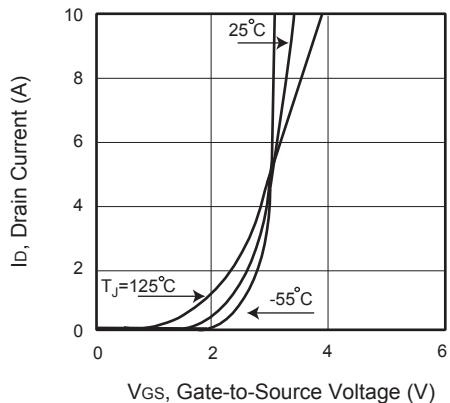
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0\text{V}$		1		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
<b>On Characteristics<sup>c</sup></b>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		2	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 4\text{A}$		63	85	$\text{m}\Omega$
		$V_{\text{GS}} = 5\text{V}, I_D = 2\text{A}$		73	100	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}} = 5\text{V}, I_D = 3.7\text{A}$	3	6		S
<b>Dynamic Characteristics<sup>d</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		400	520	pF
Output Capacitance	$C_{\text{oss}}$			120	155	pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			35	45	pF
<b>Switching Characteristics<sup>d</sup></b>						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 25\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		9	20	ns
Turn-On Rise Time	$t_r$			3	5	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			28	36	ns
Turn-Off Fall Time	$t_f$			4	6	ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 48\text{V}, I_D = 3.7\text{A}, V_{\text{GS}} = 10\text{V}$		13	17	nC
Gate-Source Charge	$Q_{\text{gs}}$			1.5		nC
Gate-Drain Charge	$Q_{\text{gd}}$			3		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current <sup>b</sup>	$I_S$				4	A
Drain-Source Diode Forward Voltage <sup>c</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 3.7\text{A}$			1.2	V

Notes :

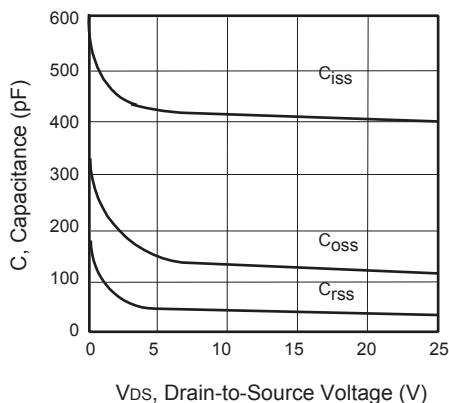
- a.Repetitive Rating : Pulse width limited by maximum junction temperature.□
- b.Surface Mounted on FR4 Board, t ≤ 10 sec.□
- c.Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.□
- d.Guaranteed by design, not subject to production testing.□



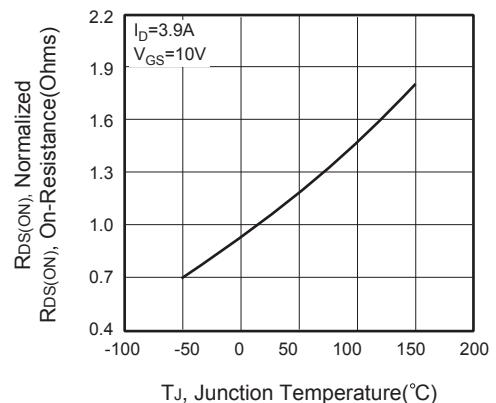
**Figure 1. Output Characteristics**



**Figure 2. Transfer Characteristics**



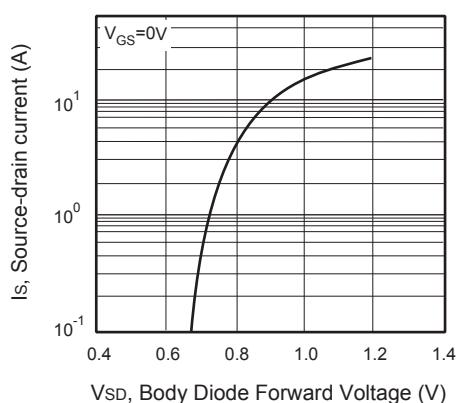
**Figure 3. Capacitance**



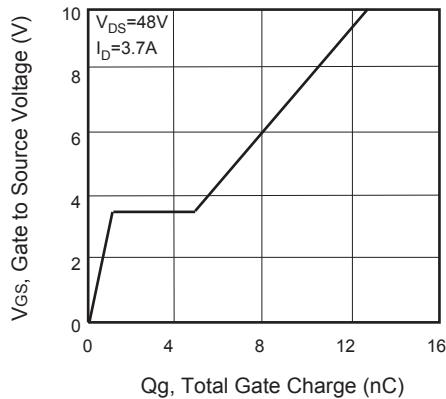
**Figure 4. On-Resistance Variation with Temperature**



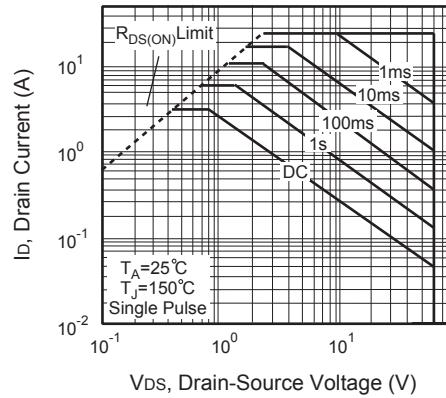
**Figure 5. Gate Threshold Variation with Temperature**



**Figure 6. Body Diode Forward Voltage Variation with Source Current**

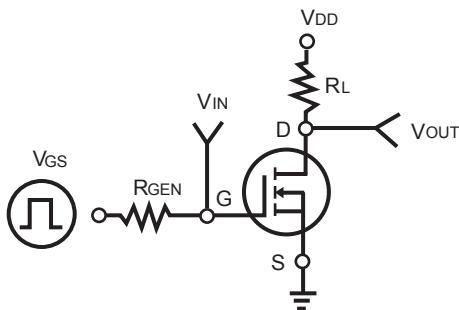


**Figure 7. Gate Charge**

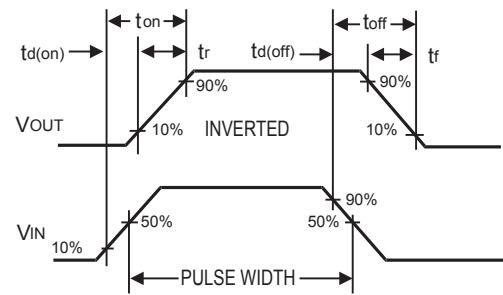


**Figure 8. Maximum Safe Operating Area**

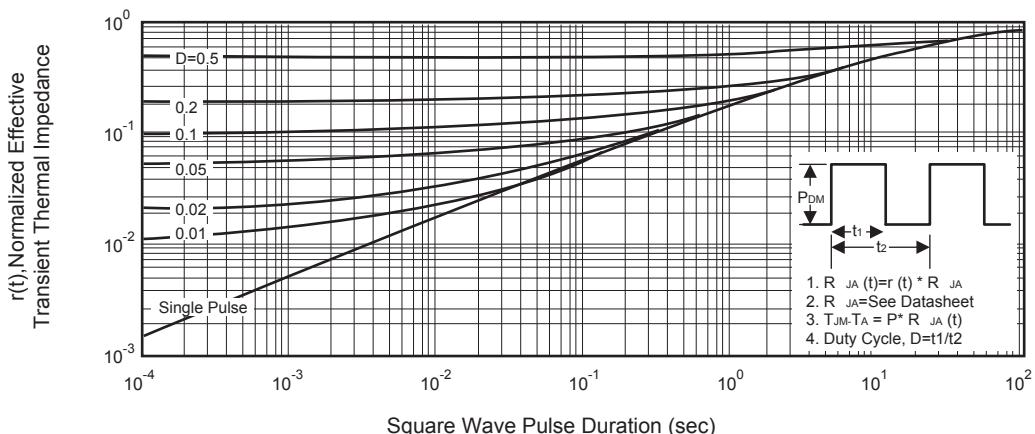
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**Figure 9. Switching Test Circuit**



**Figure 10. Switching Waveforms**



**Figure 11. Normalized Thermal Transient Impedance Curve**